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# Atomic Layer Deposition Applications 5

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**Table of Contents**

*Preface* *iii*

**Chapter 1**  
**Energy Applications I - Photovoltaics**

Synthesis of Microscale Lead Sulfide Disks by Patterned Self-Assembled Monolayer 3

*T. Usui, N. P. Dasgupta, X. Jiang, W. Lee and F. B. Prinz*

Formation of Cd<sub>x</sub>Zn<sub>1-x</sub>S Films for Photovoltaic Buffer Layers by Atomic Layer Deposition 9

*J. R. Bakke and S. F. Bent*

Quantum Dot Formation in Polymer Wires by Three-Molecule Molecular Layer Deposition (MLD) and Applications to Electro-Optic/Photovoltaic Devices 15

*T. Yoshimura, A. Oshima, D. Kim and Y. Morita*

**Chapter 2**  
**Emerging Applications I - Catalysis**

ALD of Vanadium Oxide 29

*J. Musschoot, D. Deduytsche, R. L. Van Meirhaeghe and C. Detavernier*

Remote Plasma Atomic Layer Deposition of Co<sub>3</sub>O<sub>4</sub> Thin Films 39

*M. E. Donders, H. Knoops, M. C. van de Sanden, W. M. Kessels and P. Notten*

Performance and Characterization of ALD Vanadium Oxide Catalytic Nanoliths 49

*P. C. Stair, J. Elam, J. Libera, H. Feng, M. Pellin and H. Kim*

**Chapter 3**  
**Emerging Applications II - ZnO Processes**

Structures, Properties and Applications of Functional Thin Films by ALD 59

*K. Choy*

Atomic Layer Deposition of Quantum Confined Nanostructures on Particles <i>D. M. King, X. Liang, J. Li, S. Johnson and A. W. Weimer</i>	67
Physical Characterization of Zinc Oxide Thin Films Grown by ALD <i>K. Tapily, D. Stegall, D. Gu, H. Baumgart, G. Namkoong and A. Elmoustafa</i>	85
Modeling and Characterization of ALD Grown ZnO Nanotubes and their Application to Sub-Micron Devices <i>T. M. Abdel-Fattah, D. Gu, H. Baumgart, R. Bajpai and M. Zaghloul</i>	93
The Benefits of Atomic Layer Deposition in Non-semiconductor Applications; Producing Metallic Nanomaterials and Fabrication of Flexible Display <i>H. Kim, W. Kim, H. Lee and S. Lim</i>	101

#### **Chapter 4 High Mobility Substrates**

In-situ Studies of Atomic Layer Deposition Studies on High-Mobility Channel Materials <i>M. Milojevic, A. M. Sonnet, C. L. Hinkle, H. C. Kim, E. M. Vogel, J. Kim and R. M. Wallace</i>	115
Atomic Layer Deposition of High-k Oxides on InAlN/GaN-based Materials <i>S. Abermann, C. Ostermaier, G. Pozzovivo, J. Kuzmik, O. Bethge, C. Henkel, G. Strasser, D. Pogany, C. Giesen, M. Heuken, M. Alomari, E. Kohn and E. Bertagnolli</i>	123
Effects of Surface Functionalization on Titanium Dioxide Atomic Layer Deposition on Ge Surfaces <i>P. Ardalan, C. B. Musgrave and S. F. Bent</i>	131

#### **Chapter 5 Emerging Applications III - Nanowires and Particles**

ALD Applications Beyond Outside IC Technology - Existing and Emerging Possibilities <i>M. I. Putkonen</i>	143
Formation of Silicide Nanowires by Annealing of Atomic Layer Deposition Cobalt/Silicon Core-Shell Nanowires <i>H. Lee, K. Heo, S. Hong and H. Kim</i>	157

Functionalization of Fine Particles Using Atomic and Molecular Layer Deposition <i>D. M. King, X. Liang and A. W. Weimer</i>	163
---	-----

ALD Synthesis of Tube-in-Tube Nanostructures of Transition Metal Oxides by Template Replication <i>D. Gu, P. Shrestha, H. Baumgart, G. Namkoong and T. M. Abdel-Fattah</i>	191
---	-----

## **Chapter 6** **Processing I - Equipment and Precursors**

Highly Conformal ALD of ZrO <sub>2</sub> at Higher Process Temperatures than the Conventional TEMAZr-Based Process <i>Y. Senzaki, Y. Okuyama, G. Kim, H. Kim, C. Barelli, J. Lindner, Z. Karim and S. Ramanathan</i>	201
---	-----

Recent Development of ALD Precursors for Semiconductor Devices <i>S. Wada, A. Sakurai, N. Yamada, T. Watanabe and H. Uchiuzo</i>	209
---	-----

Advanced Precursor Development for Sr and Ti Based Oxide Thin Film Applications <i>R. Katamreddy, Z. Wang, V. Omarjee, P. V. Rao, C. Dussarrat and N. Blasco</i>	217
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## **Chapter 7** **Processing II - Metal Oxide Films**

Low Temperature Plasma-Enhanced Atomic Layer Deposition of Metal Oxide Thin Films <i>S. E. Potts, L. R. van den Elzen, G. Dingemans, E. Langereis, W. Keuning, M. C. van de Sanden and W. M. Kessels</i>	233
---	-----

Atomic Layer Deposition of GdHfO <sub>x</sub> Thin Films <i>C. Adelmann, D. Pierreux, J. Swerts, E. Rosseel, X. Shi, H. Tielens, J. Kesters, S. Van Elshocht and J. Kittl</i>	243
--	-----

Novel "In-situ" <sup>2</sup> Approach to Modified ALD Processes for Nano-functional Metal Oxide Films <i>M. Tallarida, K. Karavaev and D. Schmeisser</i>	253
---	-----

Extreme Scaled Gate Dielectrics By Using ALD HfO <sub>2</sub> /SrTiO <sub>3</sub> Composite Structures	263
<i>D. Pierreux, V. Machkaoutsan, E. Tois, J. Swerts, T. Schram, C. Adelmann, S. Van Elshocht, M. I. Popovici, T. Conard, J. Tseng, L. Ragnarsson and J. W. Maes</i>	

### **Chapter 8 Processing III - Metal Fims**

Copper Oxide ALD from a Cu(I) -Diketonate: Detailed Growth Studies on SiO <sub>2</sub> and TaN	277
<i>T. Waechtler, N. Roth, R. Mothes, S. Schulze, S. Schulz, T. Gessner, H. Lang and M. Hietschold</i>	
Liquid Injection Atomic Layer Deposition of Metallic Ru Thin Films from Ru(tmhd) <sub>3</sub> and of High-k TiO <sub>2</sub> Thin Films from Ti(O-i-Pr) <sub>2</sub> (tmhd) <sub>2</sub>	289
<i>S. Kim, S. Hoffmann-Eifert and R. Waser</i>	

### **Chapter 9 Poster Session**

Plasma-Enhanced Atomic Layer Deposition of Ta(C)N Thin Films for Copper Diffusion Barrier	301
<i>K. Kim, S. Jeong, J. Yoon, Y. Kim and S. Kwon</i>	
Patterning of ALD HfO <sub>2</sub> Layers on Silicon	309
<i>R. Andreu, J. Sanchez, A. Sanchez, M. Zabala, M. Acero, J. Rafi and F. Campabadal</i>	
Optimizing the Release of ALD Grown ZnO Nanotubes from Anodic Aluminum Oxide Templates	315
<i>T. M. Abdel-Fattah, D. Gu, H. Baumgart and G. Namkoong</i>	

### **Chapter 10 Energy Applications II - Storage**

Metal Alloy Catalysts with Pt Surface Coating by Atomic Layer Deposition for Intermediate Temperature Ceramic Fuel Cells	323
<i>J. Shim, X. Jiang, S. F. Bent and F. B. Prinz</i>	

Atomic Layer Deposition for All-Solid-State 3D-Integrated Batteries 333  
*H. Knoops, M. E. Donders, L. Baggetto, M. C. van de Sanden, P. Notten and W. M. Kessels*

ALD based Metal-insulator-metal (MIM) Nanocapacitors for Energy Storage 345  
*P. Banerjee, I. Perez, L. Henn-Lecordier, S. Lee and G. W. Rubloff*

## **Chapter 11** **Capacitors and Memory**

Detailed Correlation of Electrical and Breakdown Characteristics to the Structural Properties of ALD Grown HfO<sub>2</sub>- and ZrO<sub>2</sub>-based Capacitor Dielectrics 357  
*U. Schroeder, W. Weinreich, E. Erben, J. Mueller, L. Wilde, J. Heitmann, R. Agaiby, D. Zhou, G. Jegert and A. Kersch*

Interface Analysis of Transparent Analog Capacitor Using ITO Electrodes and ALD High-k Dielectrics 367  
*S. Won, M. Huh, S. Park, S. Suh, Y. Choi, J. Heo, C. Hwang and H. Kim*

Atomic Layer Deposition of Ru and RuO<sub>2</sub> for MIMCAP Applications 377  
*C. Zhao, M. Pawlak, M. I. Popovici, M. Schaekers, E. Sleectx, E. Vancoille, D. Wouters, Z. Tokei and J. Kittl*

Plasma-Assisted ALD of TiN/Al<sub>2</sub>O<sub>3</sub> Stacks for MIMIM Trench Capacitor Applications 389  
*D. Hoogeland, K. Jinesh, F. Roozeboom, W. Besling, Y. Lamy, F. Roozeboom, M. C. van de Sanden and W. M. Kessels*

Atomic Layer Deposition of Materials for Phase-Change Memories 399  
*M. Leskelä, V. Pore, T. Hatanpää, M. Heikkilä, M. Ritala, A. Schrott, S. Raoux and S. Rossnagel*

Author Index 409